502607114 12/18/2013

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2653517

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YOUNGDAL ROH	12/18/2013
KYOUNGHEE PARK	12/18/2013
DONG JU JEON	12/18/2013
HYUNGSANG PARK	12/18/2013

RECEIVING PARTY DATA

Name:	STATS ChipPAC Ltd.	
Street Address:	10 Ang Mo Kio Street 65	
Internal Address:	#05-17/20 Techpoint	
City:	Singapore	
State/Country:	SINGAPORE	
Postal Code:	569059	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14132539

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	27-903
NAME OF SUBMITTER:	MIKIO ISHIMARU
	PAIENI

502607114 REEL: 031809 FRAME: 0526

14132539

Signature:	/Mikio Ishimaru/
Date:	12/18/2013
Total Attachments: 2 source=27-903_Assignment#page1.tif source=27-903_Assignment#page2.tif	

PATENT REEL: 031809 FRAME: 0527 Docket No.: 27-903

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

METHOD OF MANUFACTURE OF SUPPORT SYSTEM WITH FINE PITCH

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, <u>STATS ChipPAC Ltd.</u>, a Corporation of the <u>Republic of Singapore</u>, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

- 1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
- Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).
- 3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
- 4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

<u>.</u>

Docket No.: 27-903

ASSIGNMENT

5. Said Assignor(s) hereby authorizes and application to insert the serial number and fili follow:	requests the attorney(s) of record in this ing date of this application in the spaces that
Serial Number: 14/132,539	Filing Date: December 18, 2013
The said Assignor has executed and delivered t	his instrument on the date set forth below.
C/L-1	D 5 (m
YoungDal Roh	De(. 18 2013
YoungDal Roh	Date
The said Assignor has executed and delivered t	his instrument on the date set forth below. $\frac{Dec. 18. 2013}{Date}$
KyoungHee Park	Date
The said Assignor has executed and delivered t	his instrument on the date set forth below.
6 1	Date B S'
Dong Ju Jeon	Date
The said Assignor has executed and delivered t	his instrument on the date set forth below.
The second second	Do. 18 (2

Date

HyungSang Park